## Fabrication Notes:

1. Fabricate to meet or exceed IPC 6011/6012 Class 2, as definied in IPC-2221
2. Prepreg Material: 370HR or material with TG >= 170, TD >= 340
3. Minimum trace width is 6mil, minimum spacing is 6mil
4. Board finish: Electroless Nickel, Immersion Gold (ENIG)
5. Flammability: Materials to meet UL94V-0 specification
6. Apply LPI Soldermask (Blue) on both sides
7. Silkscreen on both sides using white epoxy ink or equivalent, registration to be 10mil, clear silkscreen from all exposed pads
8. Board should be panelized into 2 x 2 array. Routed with mouse-bites
9. The fabricated board shall be RoHS compliant

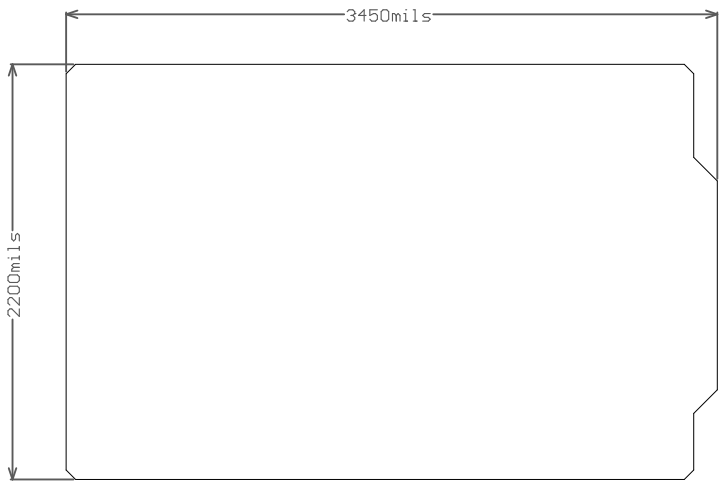
## REVISION

| REV | DESCRIPTION | DATE | BY |
|---|---|---|---|
| v2 | Added connectivity and Atmel prog | 12/11/2015 | PJB |
| vA | Updated, inverted LED polarity | 2/10/2016 | DCN |
| vB | Updated, fixed Q1, U2.97 to GND | 3/31/2016 | PJB |

4 Layer PCB 63mil +/- 10% Finished Thickness

All layer thickness and dielectric values are +/- 10% tolerance

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|---|---|---|---|---|---|
| 1 | Top Overlay | | | | |
| 2 | Top Solder | Solder Resist | 0.50mil | 3.5 | |
| 3 | Top | Copper | 1.70mil | | |
| 4 | Dielectric 1 | Composite dielectric | 4.50mil | 4.2 | |
| 5 | Layer 2 | Copper | 1.40mil | | |
| 6 | Core | Composite dielectric | 47.00mil | 4.2 | |
| 7 | Layer 3 | Copper | 1.40mil | | |
| 8 | Dielectric 3 | Composite dielectric | 4.50mil | 4.2 | |
| 9 | Bottom | Copper | 1.70mil | | |
| 10 | Bottom Solder | Solder Resist | 0.50mil | 3.5 | |
| 11 | Bottom Overlay | | | | |




LAYER USAGE

- Board Outline
- Fabrication Notes

RIGADO

For Rigado

CONFIDENTIAL

| | | |
|---|---|---|
| ENGINEER: DCN | PROJECT: BMD-300-Eval | |
| DATE: 3/31/2016 | PCB NAME: BMD-300-Eval | REV: vB |
| DWG NO: 320-00050 | FILE NAME: BMD-300-Eval.PcbDoc | SCALE: 1:1 |